



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPG20N10S4-36A	Issued	13. May 2021
MA#	MA002193052		
Package	PG-TDSON-8-10	Weight*	99.38 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.028	1.03	1.03	10340	10340
chip_2	inorganic material	silicon	7440-21-3	1.028	1.03	1.03	10340	10340
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		132	
	non noble metal	iron	7439-89-6	0.044	0.04		440	
	non noble metal	copper	7440-50-8	43.681	43.98	44.03	439565	440137
wire	non noble metal	aluminium	7429-90-5	0.825	0.83	0.83	8301	8301
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		916	
	plastics	epoxy resin	-	6.464	6.50		65050	
	inorganic material	silicondioxide	60676-86-0	38.968	39.21	45.80	392135	458101
leadfinish	non noble metal	tin	7440-31-5	1.396	1.41	1.41	14052	14052
plating	inorganic material	phosphorus	7723-14-0	0.001			15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6069	6084
solder	non noble metal	tin	7440-31-5	0.051	0.05		509	
	noble metal	silver	7440-22-4	0.063	0.06		636	
	non noble metal	lead	7439-92-1	2.415	2.43	2.54	24307	25452
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.72	2.72	27158	27193
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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